

AMENDMENTS TO THE CLAIMS:

Please replace the claims with the claims provided in the listing below wherein status, amendments, additions and cancellations are indicated.

1. (Cancelled)
2. (Previously presented) Copper alloy foil for lamination with a resin substrate, the copper alloy foil consisting essentially of 1.0-4.8 weight percent Ni, 0.1-1.4 weight percent Si, the balance copper and unavoidable impurities, the copper alloy foil having an anticorrosive coating of thickness less than 3nm, the copper alloy foil having a surface exhibiting no artificial roughening and having a surface roughness less than 2 μm expressed as ten-point average surface roughness, tensile strength greater than 650 N/mm² and conductivity greater than 40 % IACS, and 180° peel strength between the copper alloy foil and an adhesive containing an epoxy resin bonding the copper alloy foil to a resin substrate is greater than 8.0 N/cm.
3. (Currently amended) Copper alloy foil according to claim[[1 or]] 2, wherein the anticorrosive coating comprises at least one nitrogen-containing organic compound which forms a chelate with the copper.
4. (Currently amended) Copper alloy foil according to claim [[1 or]] 2, wherein the organic compound is selected from the group consisting of benzotriazole and imidazole.

5. (Currently amended) Copper alloy foil according to claim [[1 or]] 2, wherein the resin of the resin foil is a polyimide.

6. (Currently amended) A laminate comprising a copper alloy foil according to claim [[1 or]] 2 laminated with a resin substrate.

7. (Previously presented) The laminate of claim 6, further comprising a resin-containing adhesive bonding the copper alloy foil to the resin substrate.

8. (Previously presented) The laminate of claim 7, wherein the resin of the resin-containing adhesive comprises an epoxy.